FIG. 1

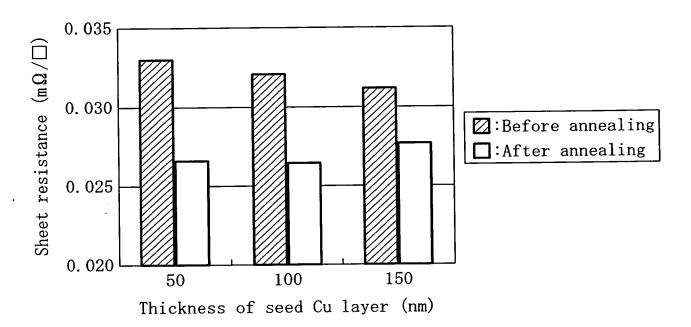
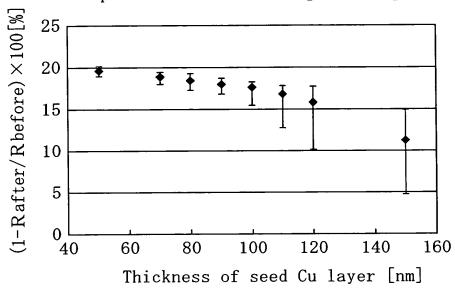
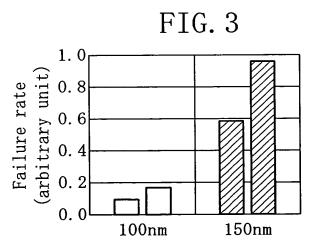


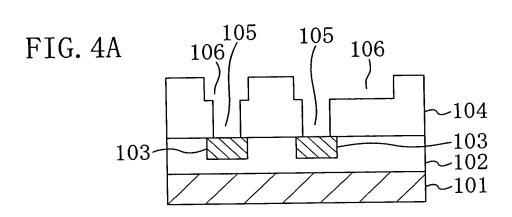
FIG. 2

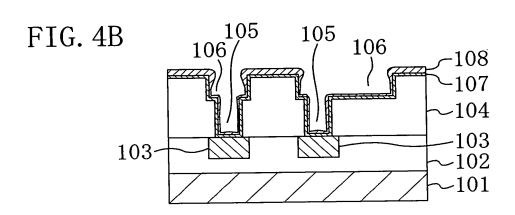
Thickness of seed Cu layer + Thickness of plated Cu film=700nm[Constant]

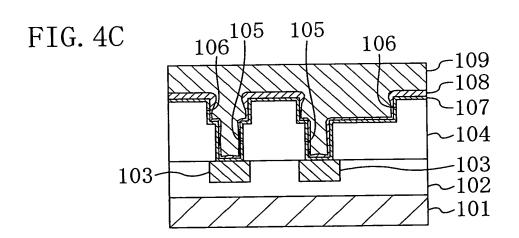


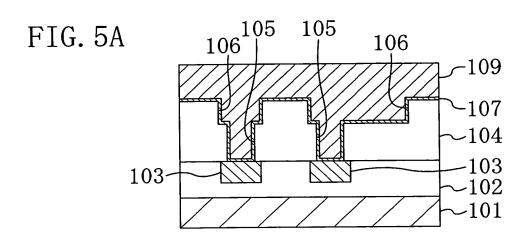


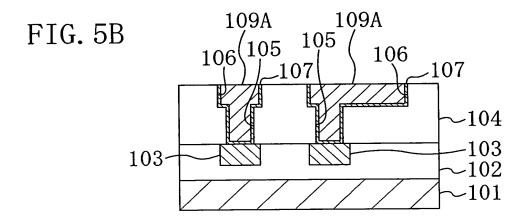
Thickness of seed layer
Results of high temperature storage test (250°C) for via resistance

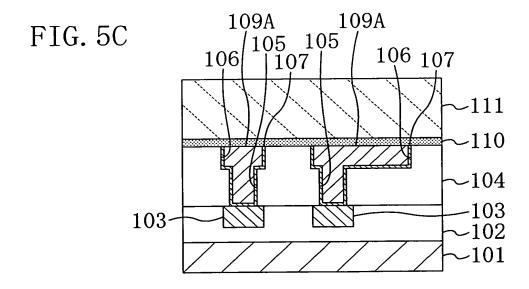












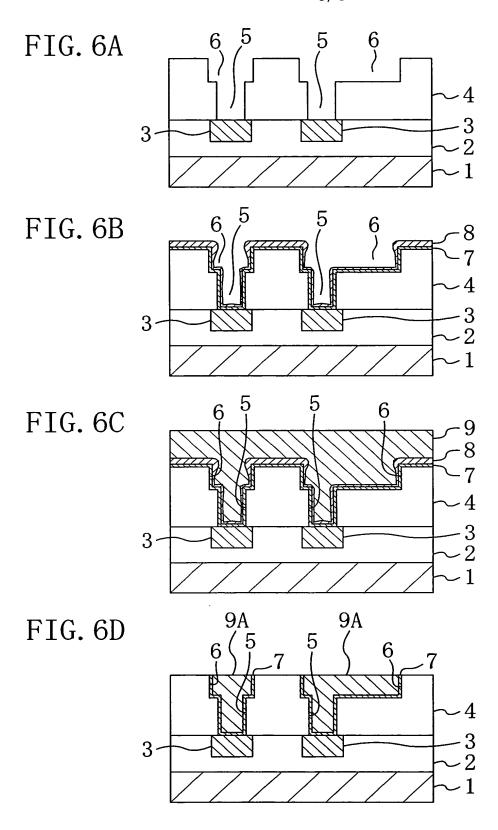


FIG. 7 PRIOR ART

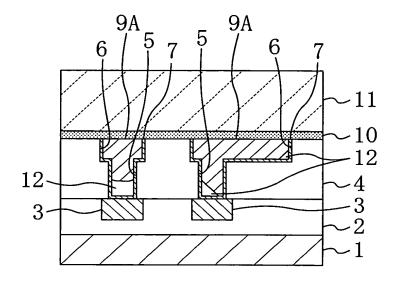


FIG. 8 PRIOR ART

